# 110V, 256A, 1.6mΩ N-channel Power SGT MOSFET

### JBL111P

#### **Features**

- $\bullet \quad \text{Excellent $R_{\text{DS(ON)}}$ and Low Gate Charge}$
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant

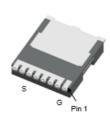
### **Product Summary**

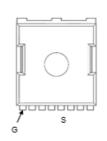
Parameters	Value	Unit
$V_{DSS}$	110	<b>V</b>
$V_{GS(th)\_Typ}$	2.9	V
$I_D(@V_{GS}=10V)$	256	Α
$R_{DS(ON)\_Typ}(@V_{GS}=10V$	1.6	mΩ

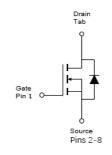




• Power Management







PowerJE®10x12

**Pin Assignment** 

**Schematic Diagram** 

### **Ordering Information**

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JBL111P	BL111P	1	Tape&Reel	PowerJE®10x12	2000	10000

# **Absolute Maximum Ratings** (@ $T_C = 25$ °C unless otherwise specified)

	<u> </u>			
Symbol	Parameter		Value	Unit
$V_{DS}$	Drain-to-Source Voltage		110	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_C = 25^{\circ}C$	256	Λ
I <sub>D</sub>	Continuous Drain Current	$T_C = 100$ °C	162	— A
I <sub>DM</sub>	Pulsed Drain Current (1)		Refer to Fig.4	А
E <sub>AS</sub>	Single Pulsed Avalanche Energ	y <sup>(2)</sup>	1624	mJ
P <sub>D</sub>	POWER Discination	$T_C = 25^{\circ}C$	357	W
		$T_C = 100$ °C	143	VV
$T_{J}$ , $T_{STG}$	Junction & Storage Temperature F	Range	-55 to 150	°C

### **Thermal Characteristics**

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	33	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.35	C/VV



### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

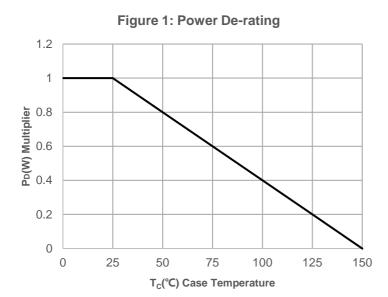
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	110	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 88V, V_{GS} = 0V$	-	-	1.0	μА
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Cha	racteristics					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0	2.9	3.7	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(4)</sup>	$V_{GS} = 10V, I_D = 20A$	-	1.6	2.2	mΩ
Dynami	c Characteristics					
$R_{g}$	Gate Resistance	f = 1MHz	-	2.6	1	Ω
C <sub>iss</sub>	Input Capacitance		8106	11348	15319	pF
C <sub>oss</sub>	Output Capacitance	$V_{GS} = 0V, V_{DS} = 55V,$ f = 1MHz	1136	1591	2147	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11/11/2	25	35	47	pF
Qg	Total Gate Charge		121	170	229	nC
Q <sub>gs</sub>	Gate Source Charge	$V_{GS} = 0 \text{ to } 10V$ $V_{DS} = 55V, I_{D} = 20A$	38	54	73	nC
$Q_{gd}$	Gate Drain("Miller") Charge	V DS = 33 V, 10 = 20/1	28	39	53	nC
<u> </u>						
	ng Characteristics	1		Π	T .	
t <sub>d(on)</sub>	Turn-On DelayTime		-	47	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 55V$	-	73	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_{D}$ = 20A, $R_{GEN}$ = 6.2 $\Omega$	-	145	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	86	-	ns
<b>Body D</b>	iode Characteristics				T	
I <sub>S</sub>	Maximum Continuous Body Diode Forward Current		-	-	256	Α
$I_{SM}$	Maximum Pulsed Body Diode Forward Current		-	-	1023	Α
$V_{SD}$	Body Diode Forward Voltage	$V_{GS} = 0V, I_{S} = 20A$	-		1.2	V
trr	Body Diode Reverse Recovery Time	I <sub>F</sub> = 20A, di/dt = 100A/us	73	103	139	ns
Qrr	Body Diode Reverse Recovery Charge	$r_F = 20A$ , $ui/ui = 100A/us$	-	335	-	nC

Notes:

- ${\bf 1.}\ Repetitive\ Rating:\ Pulse\ Width\ Limited\ by\ Maximum\ Junction\ Temperature.$
- $2.~E_{AS}~condition:~Starting~T_J=25C,~V_{DD}=55V,~V_G=10V,~R_G=25ohm,~L=3mH,~I_{AS}=32.9A,~V_{DD}=0V~during~time~in~avalanche.$
- 3.  $R_{\theta JA}$  is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB.
- 4. Pulse Test: Pulse Width  $\!\!\!\!<\!300\mu s,$  Duty Cycle  $\!\!\!<\!0.5\%.$



# **Typical Performance Characteristics**



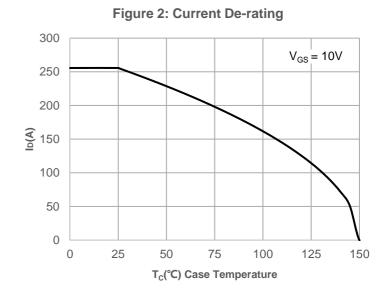
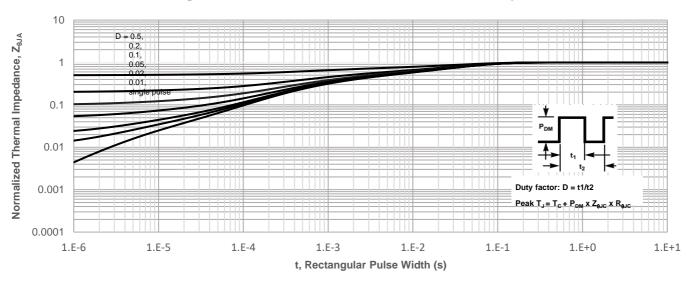
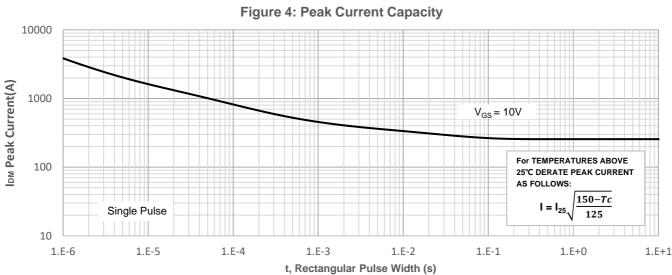


Figure 3: Normalized Maximum Transient Thermal Impedance

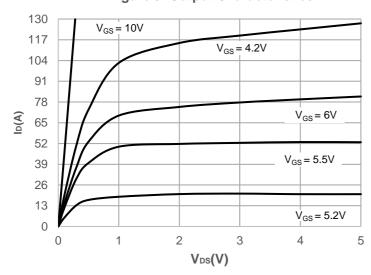






# **Typical Performance Characteristics**

**Figure 5: Output Characteristics** 



**Figure 6: Typical Transfer Characteristics** 

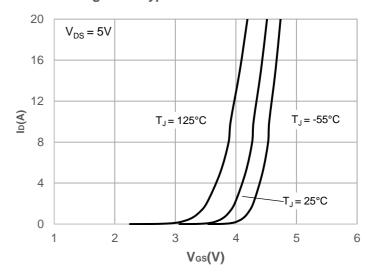
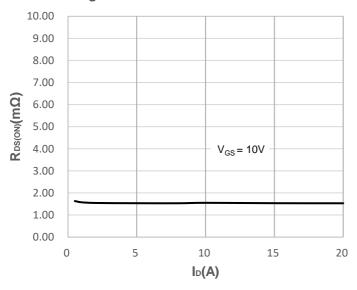
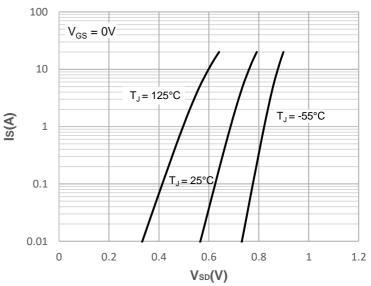


Figure 7: On-resistance vs. Drain Current



**Figure 8: Body Diode Characteristics** 



**Figure 9: Gate Charge Characteristics** 

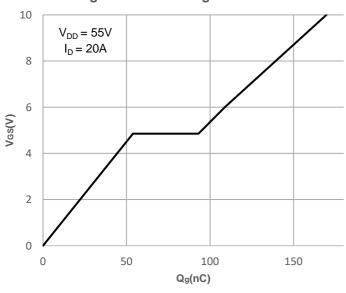
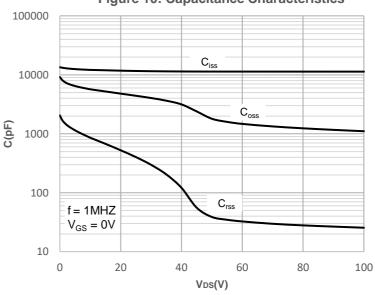


Figure 10: Capacitance Characteristics



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# **Typical Performance Characteristics**

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

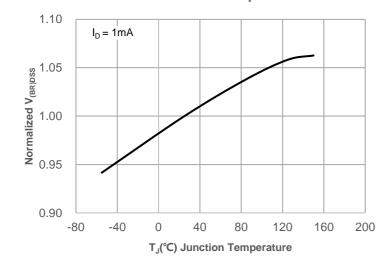


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

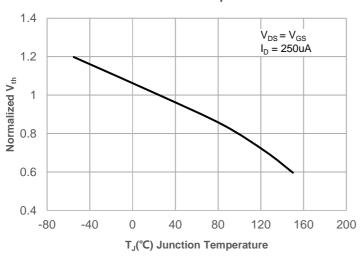


Figure 15: Maximum Safe Operating Area

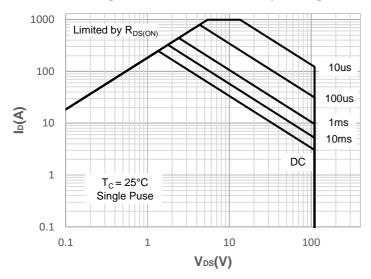
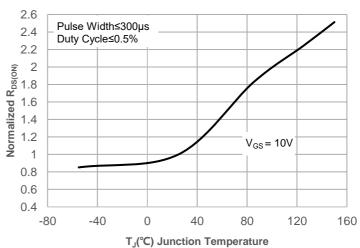
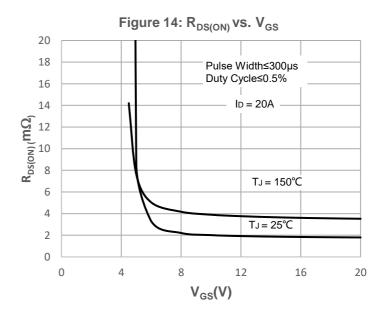


Figure 12: Normalized on Resistance vs. Junction Temperature







# **Test Circuit**

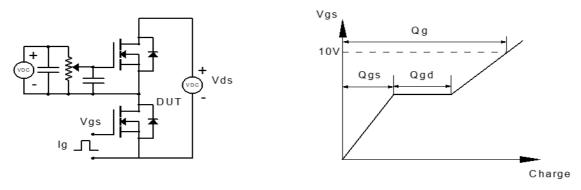


Figure 1: Gate Charge Test Circuit & Waveform

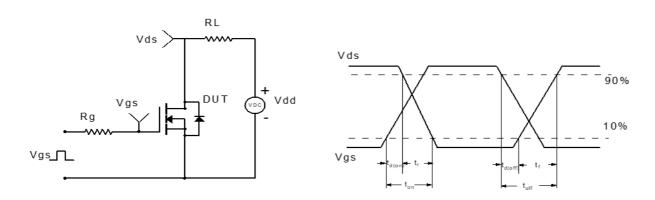


Figure 2: Resistive Switching Test Circuit & Waveform

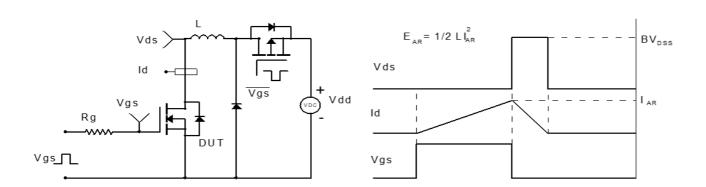


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

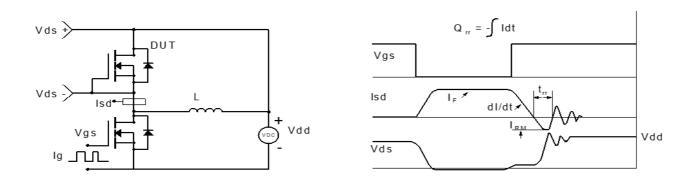


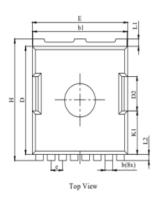
Figure 4: Diode Recovery Test Circuit & Waveform

M

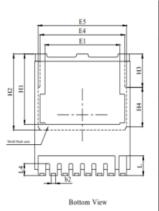


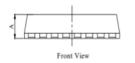
### Package Mechanical Data(PowerJE®10x12)

### Package Outlines



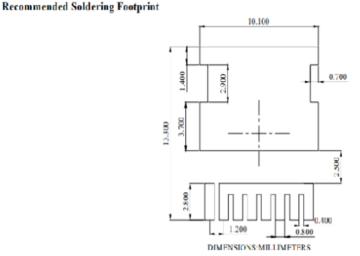






NOTES:

- Dimension and tolerance per ASME Y14.5M, 1994.
- 2. All dimensions in millimeter.
- Dimensions do not include burrs or mold flash. Mold flash or burrs does not exceed 0.150mm.



DIM.	MILLIMETER				
DIIVI.	MIN	NOM	MAX		
Α	2.20	2.30	2.50		
b	0.70 0.80 0.90				
bl	9.70 9.80 9.90				
b2	0.42 0.46 0.50				
С	0.40	0.50	0.65		
D	10.28	10.38	10.58		
D2	3.30				
E	9.70 9.90 10.10				
E1	7.80				
E4	8.80				
E5	9.20				
e	1.20(BSC)				
Н	11.48	11.68	11.88		
H	6.55	6.75	6.85		
H2	7.30				
H3	3.20				
H4	3.80				
K1	4.18				
L	1.70 1.90 2.10				
L1	0.70				
L2	0.60				
L4	1.00	1.15	1.30		

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